## TITLE: ENGINEERING CONTROL DRAWING.

PART IDENTIFIER: SMT2525TALNF

**DESCRIPTION:** SURFACE MOUNT TERMINATION, TUNED FOR TELECOM BANDS, LEAD FREE

ASSEMBLY DWG: 1102014

## 1.0 SPECIFICATIONS:

- 1.1 ELECTRICAL:
  - 1.1.1 IMPEDANCE: 50Ω NOMINAL.
  - 1.1.2 FREQUENCY: DC 4 GHZ.
  - 1.1.3 VSWR: 1.2:1 MAX.
  - 1.1.4 INPUT POWER:
    - 1.1.4.1 60 WATTS. CHIP SOLDERED TO MOUNTING SURFACE. MOUNTING SURFACE TEMPERATURE MAINTAINED AT 100 °C MAXIMUM. APPLY LINEAR DE-RATING OF INPUT POWER TO 0 WATTS AT 150 °C.
- 1.2 MECHANICAL:
  - 1.2.1 OUTLINE DWG: SEE SHEET 2.
  - 1.2.2 WORKMANSHIP: PER MIL-PRF-55342
  - 1.2.3 THERMAL IMPEDANCE  $(R_{\odot})$ 
    - .2.3.1 0.833 °C / WATT  $R_{\odot}$  FROM RESIST FILM TO MOUNTING SURFACE DIRECTLY UNDER CENTER OF CHIP. CHIP SOLDERED DIRECTLY TO MOUNTING SURFACE.
  - 1.2.4 FILM TEMPERATURE (T<sub>F</sub>)
    - 1.2.4.1 200 °C ABSOLUTE MAXIMUM FILM TEMPERATURE. DE-RATE TO 150 °C MAXIMUM FILM TEMPERATURE FOR ALL MILITARY/HIGH-RELIABILITY APPLICATIONS.
  - 1.2.5 THERMAL
    - 1.2.5.1 DETERMINE MAXIMUM MOUNTING SURFACE TEMPERATURE BY APPLYING THE FOLLOWING FORMULA:

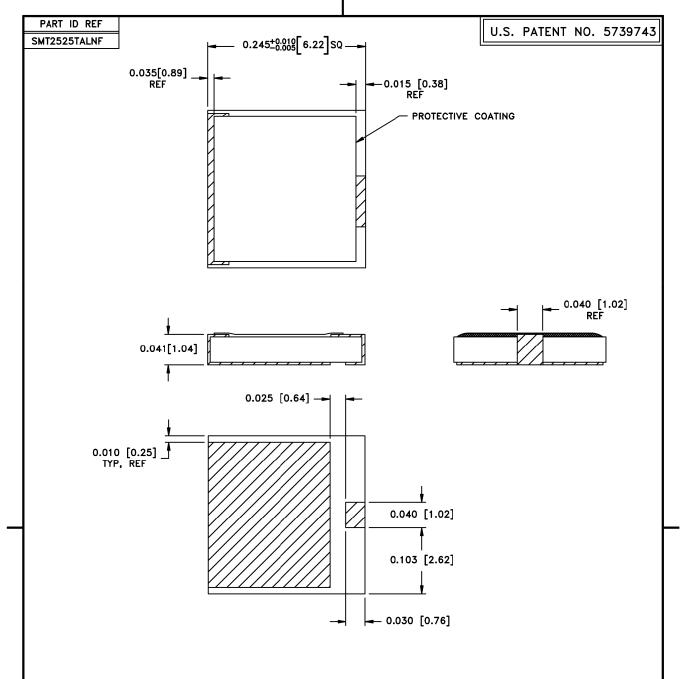
 $T_S = T_F - (P_{MAX} X R_{\Theta})$ 

WHERE: T<sub>S</sub> = MAXIMUM MOUNTING SURFACE TEMPERATURE

 $T_F$  = MAXIMUM FILM TEMPERATURE  $P_{MAX}$  = MAXIMUM APPLIED INPUT POWER  $R_{\odot}$  = CHIP THERMAL IMPEDANCE.

- 1.3 ENVIRONMENTAL:
  - 1.3.1 TEMPERATURE RANGE:
    - 1.3.1.1 NON-OPERATING: -55°C TO +150°C. 1.3.1.2 OPERATING: -55°C TO +150°C.
- 2.0 UNIT MARKING: NONE.
- 3.0 QUALITY ASSURANCE:
  - 3.1 SAMPLE INSPECT PER ANSI/ASQC Z1.4 GENERAL INSPECTION, LEVEL II, AQL = 1.0.
    - 3.1.1 VISUAL AND MECHANICAL PER 824W154.
    - 3.1.2 DC RESISTANCE:  $50\Omega \pm 5\%$ .
  - 3.2 DATA REQUIREMENTS:
    - 3.2.1 NO TEST DATA REQUIRED FOR CUSTOMER.
    - 3.2.2 DATA RETENTION 24 MONTHS.
- 4.0 PACKAGING: STANDARD PACK PER 755W002.

EMC TECHNOLOGY	CAGE CODE # 24602		DWG#	1010635000			
8851 SW OLD KANSAS AVE.	CHANGE NOTICE	EN 10-E0362	REV LVL	С			
STUART, FL 34997			SHEET	1	OF	2	



## MECHANICAL SPECIFICATIONS

SUBSTRATE:

- ALUMINUM NITRIDE, ASTM F356.

MATERIAL TERMINAL : THICK FILM, LEAD FREE PLATING. ROHS COMPLIANT. MATERIAL

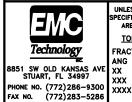
**RESIST:** MATERIAL - THICK FILM.

METRIC EQUIVALENTS GIVEN IN [mm] ARE FOR REFERENCE INFORMATION ONLY

## POWER RATING AND DERATING 100% SAFE OPERATING AREA 0%\_55 75 125 100

TEMPERATURE IN \*C

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UNLESS SPECIFIED ARE II		ISIONS		
TOLERANCES				
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PERCENT OF RATED POWER

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